### SMD1210 Series

### ROHS

#### **Surface Mount Resettable PTCs**

### **Description**

The SMD1210 Series PTC provides surface mount over-current protection for applications where space is at a premium and reset table protection is desired.

#### **Features**

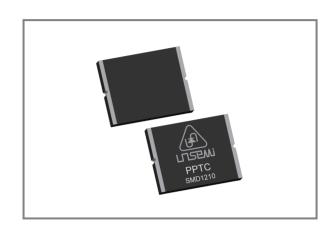
- ◆ RoHS compliant, Lead-Free and Halogen-Free
- ◆ Faster tripping, 1210 Dimension
- ◆ Compact design saves board space
- ◆ Compatible with high temperature solders
- ◆ Agency recognition: UL
- ◆ Low-profile

#### **Applicable**

- Battery PCM
- ◆ PDAs & Charger, Analog & digital line card
- Digital cameras
- ◆ General electronics
- ♦ USB peripherals
- Power ports



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### **Electrical Parameters**

Part Number	Marking	l hold	I trip	V max	71		ım Time Trip	Res	istance	
Fait Nullipel	Marking	(A)	(A)	(Vdc)	(A)	(W)	Current (A)	Time (Sec.)	R min (Ω)	R 1max (Ω)
SMD1210-005	UZ	0.05	0.15	60	100	0.6	0.25	1.50	2.80	50.00
SMD1210-010	UN	0.10	0.30	30	100	0.6	0.50	0.60	0.80	15.00
SMD1210-020	UF	0.20	0.40	30	100	0.6	8.0	0.02	0.40	5.00
SMD1210-035	UM	0.35	0.75	16	100	0.6	8.0	0.20	0.20	1.30
SMD1210-035/30V	UM	0.35	0.75	30	100	0.6	8.0	0.20	0.20	1.30
SMD1210-050	UG	0.50	1.00	16	100	0.6	8.0	0.10	0.18	0.90
SMD1210-050/30V	UG	0.50	1.00	30	100	0.6	8.0	0.10	0.18	0.90
SMD1210-075	US	0.75	1.50	6	100	0.6	8.0	0.10	0.07	0.40
SMD1210-075/24V	US	0.75	1.50	24	100	0.6	8.0	0.10	0.07	0.45
SMD1210-110	UU	1.10	2.20	6	100	0.6	8.0	0.30	0.05	0.21
SMD1210-110/12V	UU	1.10	2.20	12	100	0.8	8.0	0.30	0.05	0.25
SMD1210-110/16V	UU	1.10	2.20	16	100	0.8	8.0	0.30	0.05	0.25
SMD1210-150	UK	1.50	3.00	6	100	0.8	8.0	0.50	0.03	0.11
SMD1210-175	UW	1.75	3.50	6	100	0.8	8.0	0.60	0.02	0.08
SMD1210-200	UY	2.00	4.00	6	100	0.8	8.0	1.00	0.015	0.07

I hold= Hold current: maximum current device will pass without tripping in 25°C still air.

I trip= Trip current: minimum current at which the device will trip in 25°C still air.

V max= Maximum voltage device can withstand without damage at rated current (Imax)

I max= Maximum fault current device can withstand without damage at rated voltage (Vmax)

Pdtyp.= Power dissipated from device when in the tripped state at 25°C still air.

R min= Minimum resistance of device in initial (un-soldered) state.

R max= Maximum resistance of device in initial (un-soldered) state.

R 1max= Maximum resistance of device at 25°C measured one hour after tripping.



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# **Temperature Rerating Chart-I hold (A)**

				Ambient (	Operation Te	mperature			
Part Number	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
				Н	old Current (	(A)			
SMD1210-005	0.08	0.07	0.06	0.05	0.04	0.04	0.03	0.03	0.02
SMD1210-010	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.05
SMD1210-020	0.29	0.26	0.22	0.20	0.16	0.14	0.13	0.11	0.08
SMD1210-035	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
SMD1210-035/30V	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
SMD1210-050	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28
SMD1210-050/30V	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28
SMD1210-075	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
SMD1210-075/24V	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
SMD1210-110	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210-110/12V	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210-110/16V	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210-150	2.30	2.02	1.76	1.50	1.24	1.11	1.00	0.85	0.65
SMD1210-175	2.45	2.22	2.01	1.75	1.45	1.26	1.10	0.98	0.80
SMD1210-200	2.60	2.44	2.35	2.00	1.78	1.67	1.50	1.45	1.10

# **Test Procedures and Requirement**

Test Item	Test Conditions	Accept/Reject Criteria
Initial Resistance	In still air at 25°C	RMIN ≤ R ≤ R1MAX
Time to Trip	Specified current, VMAX, 25°C	T ≤ Maximum Time to Trip
Hold Current	30min, at IH, 25°C	No trip
Trip Cycle Life	VMAX, Imax, 100cycles	No arcing or burning
Trip Endurance	VMAX, 1 hour	No arcing or burning

### **Physical Characteristics**

Terminal Materials	Tin-Plated Nickle-copper
Soldering Zone	Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.



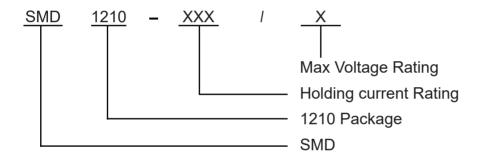


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# **Environmental Specifications**

Test Item	Test Conditions	Resistance Change
Passive Aging	85°C ,1000 hours	±10% typical
Humidity Aging	85°C/85%RH.1000 hours	±5% typical
Thermal Shock	MIL-STD-202,Method 107G +85 °C/-40°C ,20 times	-30% typical
Solvent Resistance	MIL-STD-202,Method 215	No change
Vibration	ML-STD-883C,Test Condition A	No change

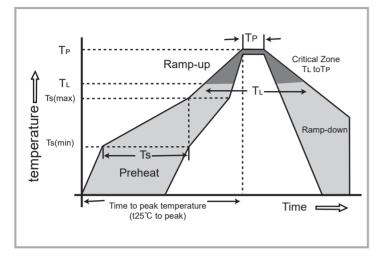
### **Part Numbering System**





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### **Soldering Parameters**



- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- ◆ Recommended maximum paste thickness is 0.25mm(0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHs lead free process. Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Reflow	Condition	Lead–free assembly		
	-Temperature Min (Ts <sub>(min)</sub> )	150°C		
Pre Heat	-Temperature Max (Ts <sub>(max)</sub> )	200°C		
	- Time (min to max) (Ts)	60 -120 Seconds		
	e ramp up rate ( Liquidus L) to peak	3°C/second max		
Ts <sub>(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max		
Reflow	- Temperature (TL) (Liquidus)	217°C		
Rellow	- Time (min to max) (Ts)	60 -150 Seconds		
Peak Te	mperature (TP)	260 +0/-5°C		
	thin 5°C of actual peak ature (TP)	30 Seconds		
Ramp-d	lown Rate	3°C/second max		
Time 25	°C to peak Temperature (TP)	8 minutes Max		
Do not	exceed	260°C		

#### Caution:

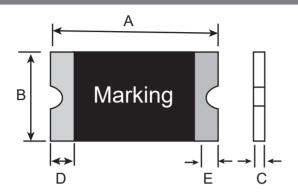
- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements
- 2. Operation beyond the specified rating may result in damage and possible arcing and flame.
- 3. PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

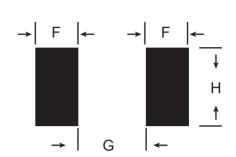




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### **Dimensions Unit: mm**





Part Number		Ą	l l	3	С		D	Е
Part Number	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD1210-005	3.00	3.43	2.35	2.80	0.60	1.25	0.15	0.10
SMD1210-010	3.00	3.43	2.35	2.80	0.60	1.25	0.15	0.10
SMD1210-020	3.00	3.43	2.35	2.80	0.50	1.00	0.15	0.10
SMD1210-035	3.00	3.43	2.35	2.80	0.35	0.90	0.15	0.10
SMD1210-035/30V	3.00	3.43	2.35	2.80	0.35	1.00	0.15	0.10
SMD1210-050	3.00	3.43	2.35	2.80	0.35	0.90	0.15	0.10
SMD1210-050/30V	3.00	3.43	2.35	2.80	0.60	1.20	0.15	0.10
SMD1210-075	3.00	3.43	2.35	2.80	0.35	0.85	0.15	0.10
SMD1210-075/24V	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210-110	3.00	3.43	2.35	2.80	0.40	1.00	0.15	0.10
SMD1210-110/12V	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210-110/16V	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210-150	3.00	3.43	2.35	2.80	0.60	1.40	0.15	0.10
SMD1210-175	3.00	3.43	2.35	2.80	0.60	1.40	0.15	0.10
SMD1210-200	3.00	3.43	2.35	2.80	0.60	1.50	0.15	0.10

# Layout Dimensions Unit: mm

Part Number	F	G	Н	
i ait number	Normal Value	Normal Value	Normal Value	
SMD1210 Series	1.0±0.1	2.0±0.1	2.5±0.1	



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# **Ordering Information**

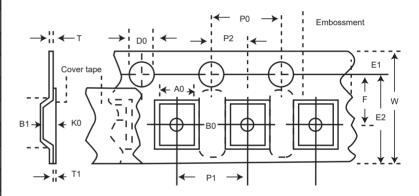
Part Number	Quantity
SMD1210-005 SMD1210-075	4,000 pcs/Reel
SMD1210-110 SMD1210-200	4,000 pcs/Reel
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### **Tape Specification and Reel Specifications**

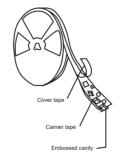
Coverning Specifications EIA 481-1(Unit:mm)					
W	8.00±0.10				
P0	4.00±0.10				
P1	4.00±0.10				
P2	2.00±0.05				
A0	0.95±0.10				
В0	1.85±0.10				
D0	1.55±0.05				
F	3.50±0.05				
E1	1.75±0.10				
Т	0.20±0.02				
Leader min.	390				
Traile min.	160				

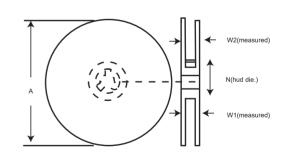
Reel Dimensions					
A	178±1.0				
N	59±1.0				
W1	8.5 + 1.0/-0.2				
W2	12.0±1.0				

# **ELA Tape Component Dimentions**



#### **EIA Reel Dimentions**







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